

Bill of Materials

TI DESIGNS

TIDM-NFC-EZ430-MODULE

Reference	Qty	Value	Manufacturer Part Number	PCB Footprint
C1	1	10uF	C1608X5R0J106M	C0603
C2	1	220nF	GRM155R60J224KE01D	C0402
C3, C4, C24, C25, C26	5	27pF	CC0402JRNPO9BN270	C0402
C5, C7, C9, C11, C34	5	2.2uF	C1005X5R0G225M	C0402
C6, C8, C10, C12, C35	5	100nF	C1005X5R0J104K	C0402
C15, C16	2	1500pF	GRM155R71H152KA01D	C0402
C17, C18	2	1200pF	GRM155R71H122KA01D	C0402
C19	1	220pF	CC0402JRNPO8BN221	C0402
C20, C22	2	680pF	C1005X7R1H681K	C0402
C21, C27	2	10pF	CC0402JRNPO9BN100	C0402
C23	1	100pF	GRM1555C1H101JZ01D	C0402
C28	1	68pF	C1005C0G1H680J	C0402
D3	1	red	LTST-C190KRKT	CHIP-LED0603
D4	1	green	LTST-C190KGKT	CHIP-LED0603
L2	1	150nH	744762215A	L2825P / 1008
L3	1	330nH	744762233A	L2825P / 1008
R1	1	10	RC0402JR-0710RL	R0402_GE
R2	1	47k	RC0402JR-0747KL	R0402_GE
R4	1	10k	RC0402JR-0710KL	R0402_GE
R7, R8	2	1k	RC0402JR-071KL	R0402_GE

Reference	Qty	Value	Manufacturer Part Number	PCB Footprint
R11	1	1.2k	RC0402JR-071K2L	R0402
R12, R13	2	330R	RC0402JR-07330RL	R0402_GE
ST1	1	1X06	LPPB061NFFN-RC	1X06
U1	1	TRF7970A	TRF7970ARHBR/BT	QFN(RHB)32
U2	1	MSP430G2553	MSP430G2553RHBR/BT	RHB32
UFL1	1	U.FL	U.FL-R-SMT-1(10)	U.FL
Y1	1	13.56MHz	7A-13.560MAAJ-T	CRYSTAL-SMD-5X3.2

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